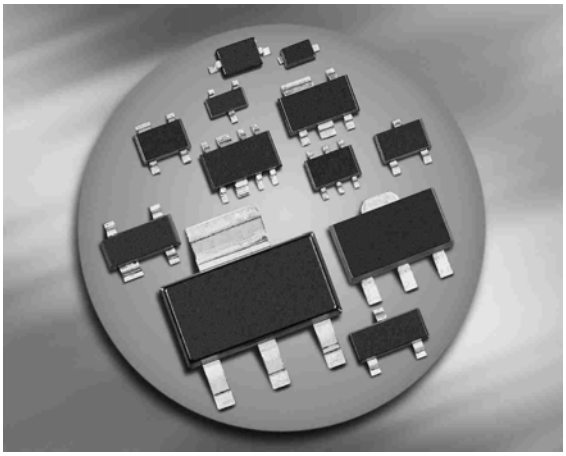
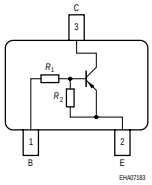
PNP Silicon Digital Transistor

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor *(R_1 = 4.7kΩ , R_2 = 4.7kΩ)*



BCR162/F/L3
BCR162T



Type	Marking	Pin Configuration						Package
BCR162	WUs	1=B	2=E	2=C	-	-	-	SOT23
BCR162F	WUs	1=B	2=E	2=C	-	-	-	TSFP-3
BCR162L3	WU	1=B	2=E	2=C	-	-	-	TSLP-3-4
BCR162T	WUs	1=B	2=E	2=C	-	-	-	SC75

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	50	V
Collector-base voltage	V_{CBO}	50	
Emitter-base voltage	V_{EBO}	10	
Input on voltage	$V_{i(on)}$	15	
Collector current	I_C	100	mA
Total power dissipation-	P_{tot}		mW
BCR162, $T_S \leq 102°C$		200	
BCR162F, $T_S \leq 128°C$		250	
BCR162L3, $T_S \leq 135°C$		250	
BCR162T, $T_S \leq 109°C$		250	
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[1)]	R_{thJS}		K/W
BCR162		≤ 240	
BCR162F		≤ 90	
BCR162L3		≤ 60	
BCR162T		≤ 165	

[1]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

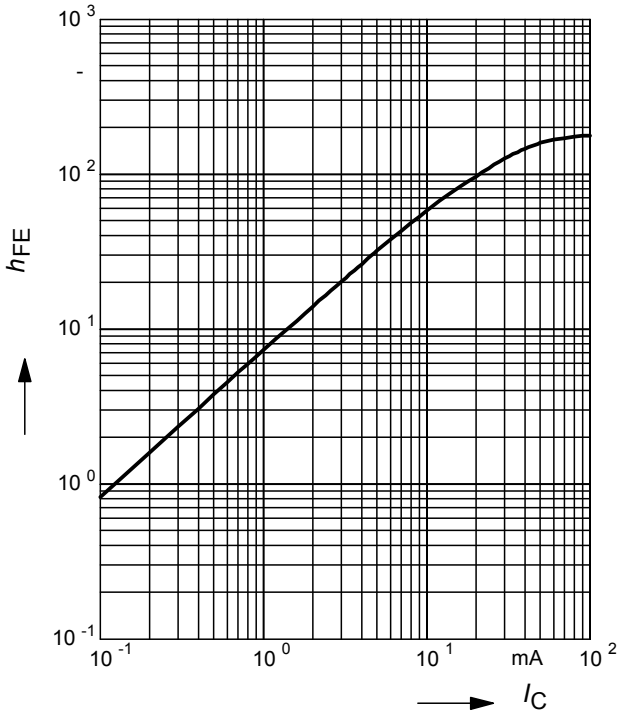
Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage I_C = 100 µA, I_B = 0	$V_{(BR)CEO}$	50	-	-	V
Collector-base breakdown voltage I_C = 10 µA, I_E = 0	$V_{(BR)CBO}$	50	-	-	
Collector-base cutoff current V_{CB} = 40 V, I_E = 0	I_{CBO}	-	-	100	nA
Emitter-base cutoff current V_{EB} = 10 V, I_C = 0	I_{EBO}	-	-	1.61	mA
DC current gain[1)] I_C = 5 mA, V_{CE} = 5 V	h_{FE}	20	-	-	-
Collector-emitter saturation voltage[1)] I_C = 10 mA, I_B = 0.5 mA	V_{CEsat}	-	-	0.3	V
Input off voltage I_C = 100 µA, V_{CE} = 5 V	$V_{i(off)}$	0.8	-	1.5	
Input on voltage I_C = 2 mA, V_{CE} = 0.3 V	$V_{i(on)}$	1	-	2.5	
Input resistor	R_1	3.2	4.7	6.2	kΩ
Resistor ratio	R_1/R_2	0.9	1	1.1	-
AC Characteristics					
Transition frequency I_C = 10 mA, V_{CE} = 5 V, f = 100 MHz	f_T	-	200	-	MHz
Collector-base capacitance V_{CB} = 10 V, f = 1 MHz	C_{cb}	-	3	-	pF

[1]Pulse test: t < 300µs; D < 2%

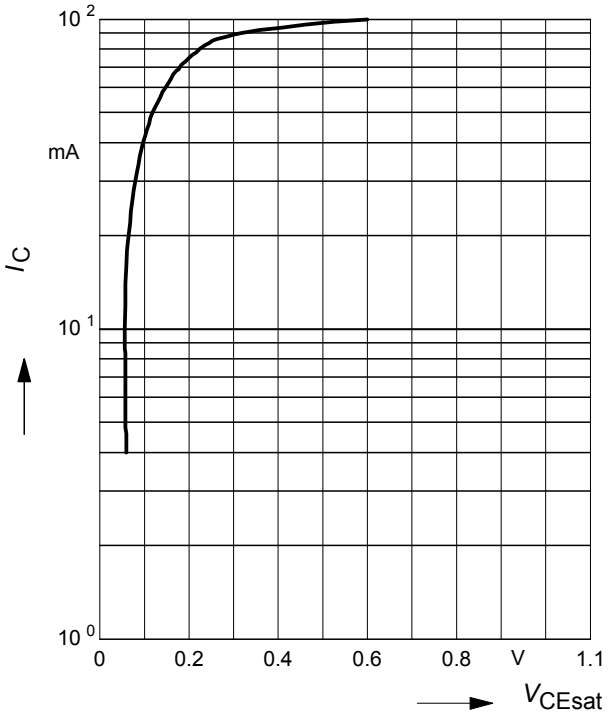
DC current gain $h_{FE} = f(I_C)$

V_{CE} = 5 V (common emitter configuration)



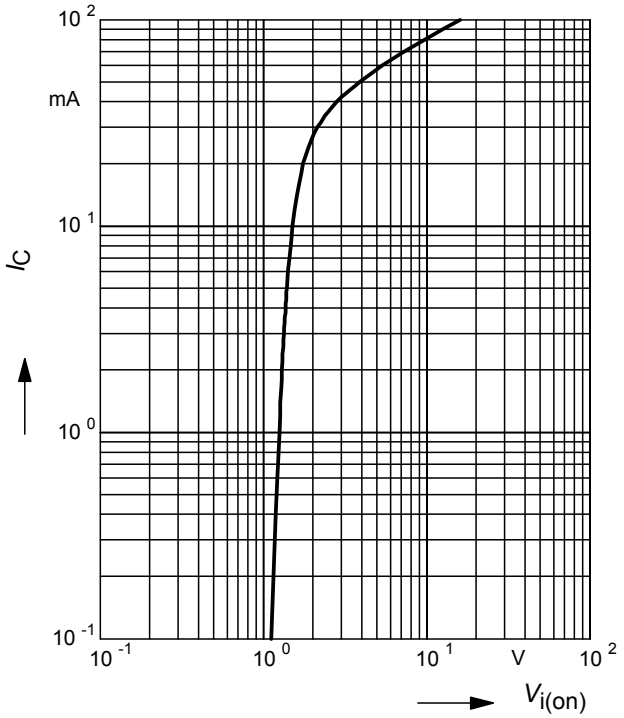
Collector-emitter saturation voltage

$V_{CEsat} = f(I_C)$, h_{FE} = 20



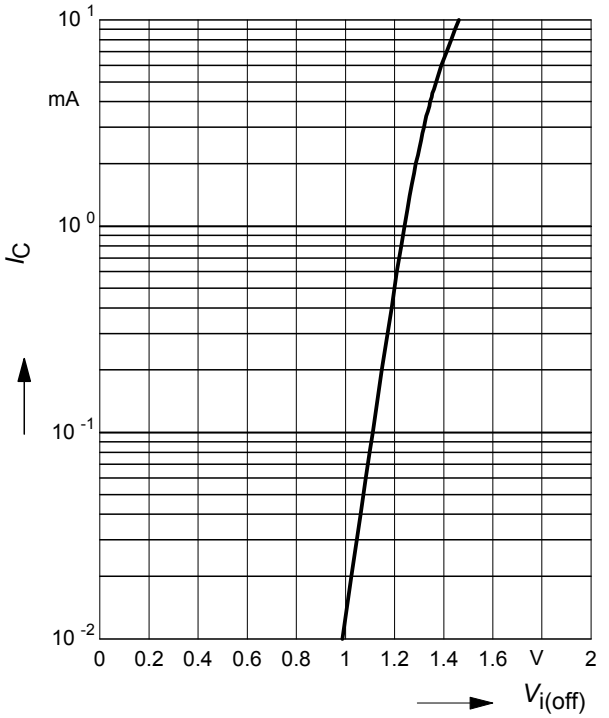
Input on Voltage $V_{i(on)} = f(I_C)$

V_{CE} = 0.3V (common emitter configuration)

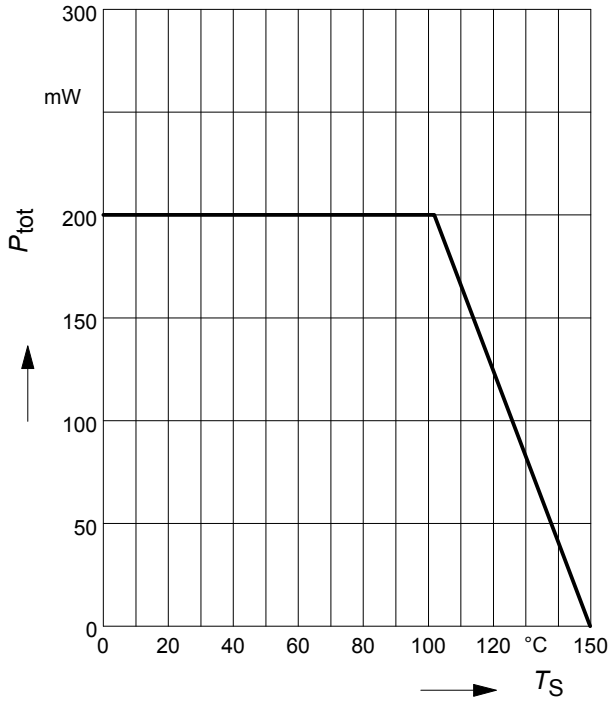


Input off voltage $V_{i(off)} = f(I_C)$

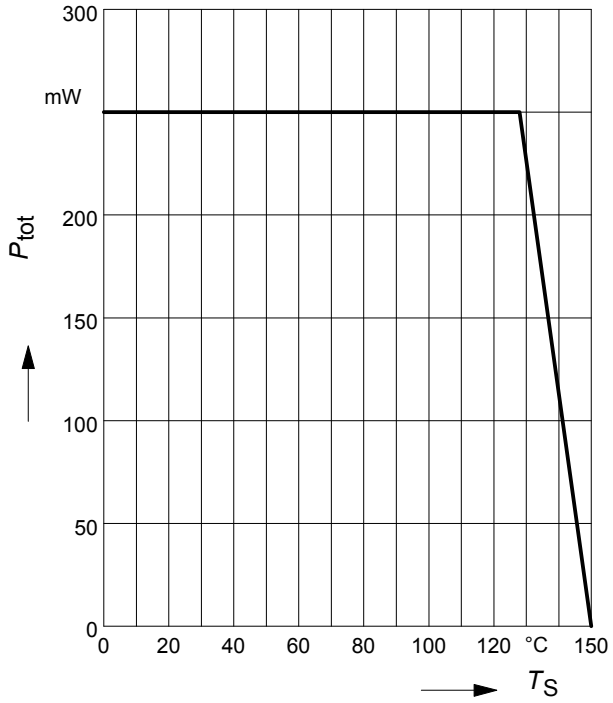
V_{CE} = 5V (common emitter configuration)



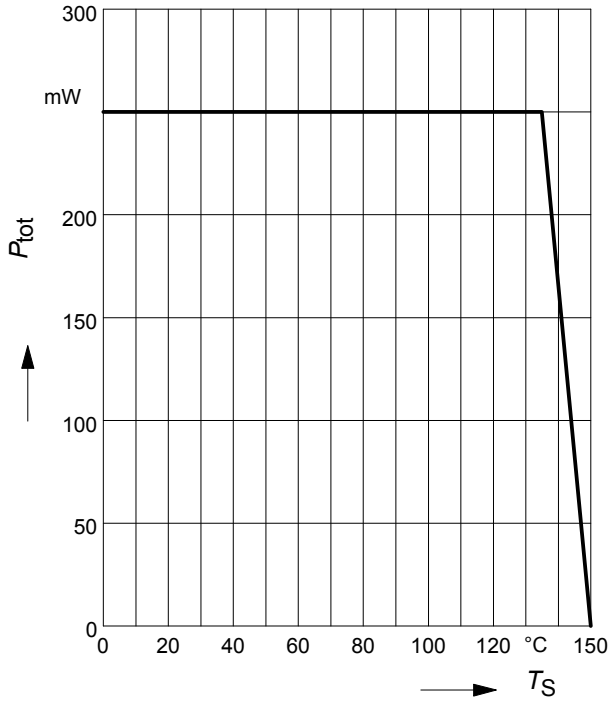
Total power dissipation $P_{tot} = f(T_S)$
BCR162



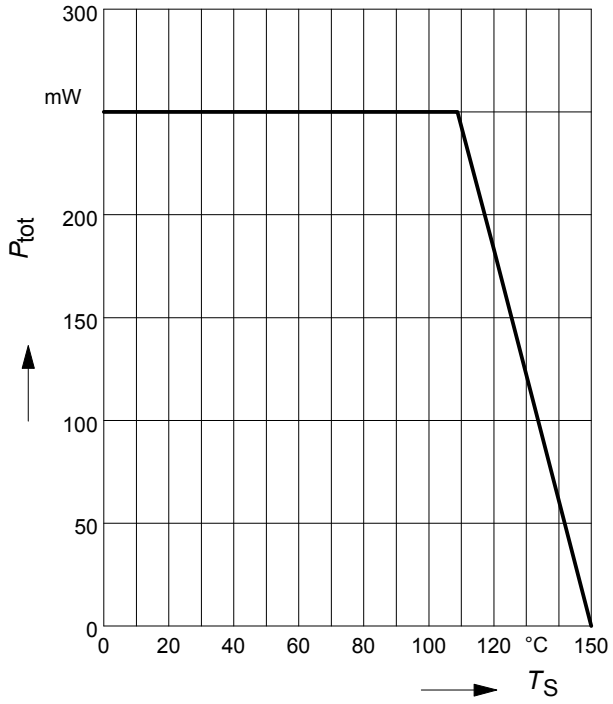
Total power dissipation $P_{tot} = f(T_S)$
BCR162F



Total power dissipation $P_{tot} = f(T_S)$
BCR162L3

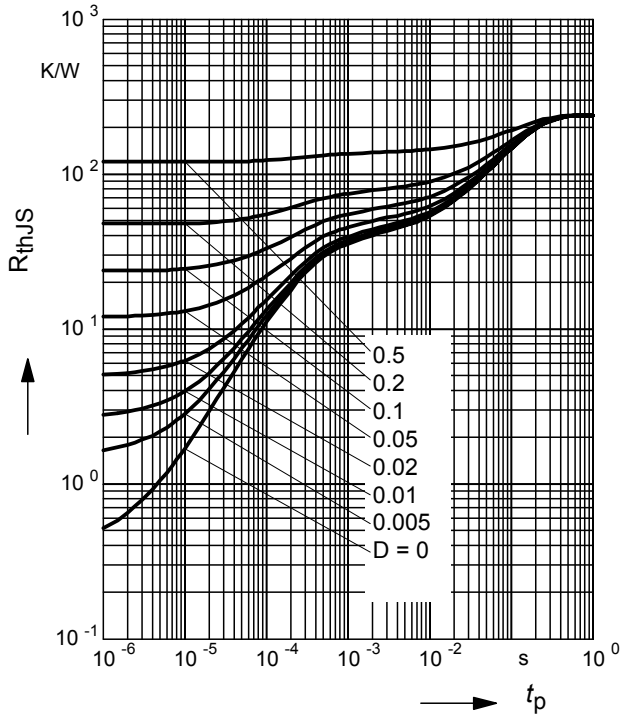


Total power dissipation $P_{tot} = f(T_S)$
BCR162T



Permissible Pulse Load $R_{thJS} = f(t_p)$

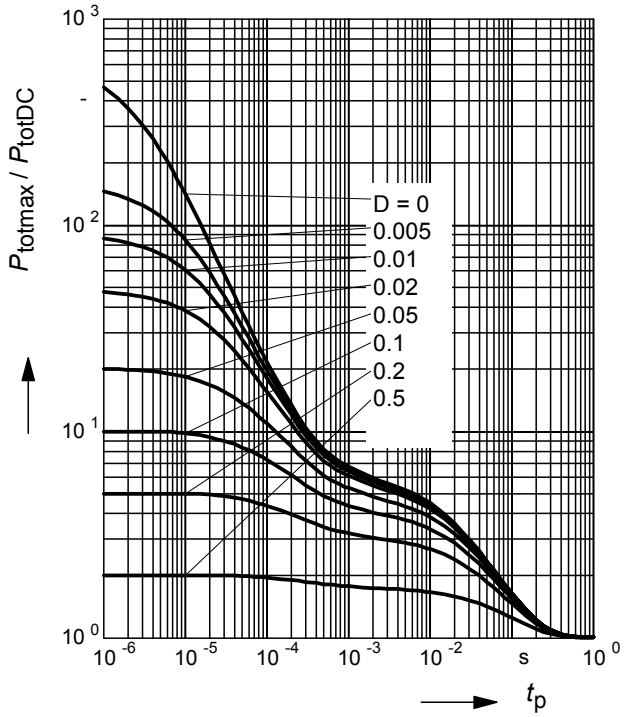
BCR162



Permissible Pulse Load

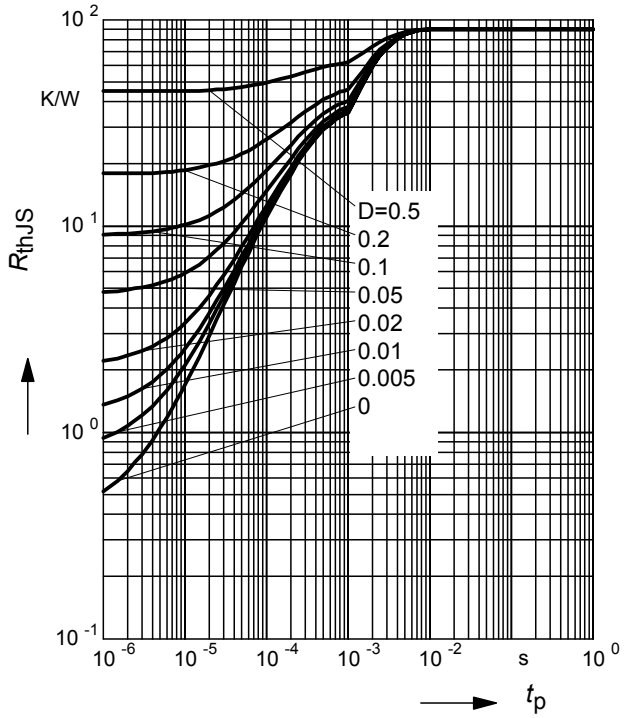
$P_{totmax}/P_{totDC} = f(t_p)$

BCR162



Permissible Puls Load $R_{thJS} = f(t_p)$

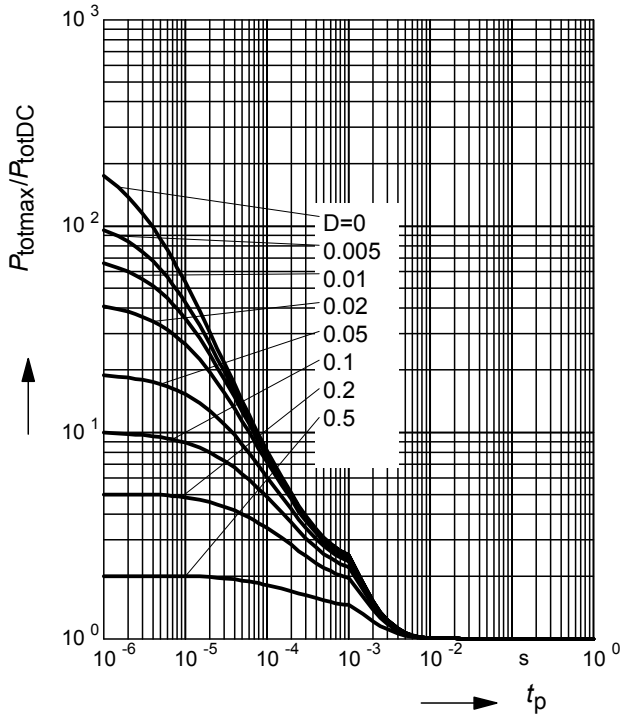
BCR162F



Permissible Pulse Load

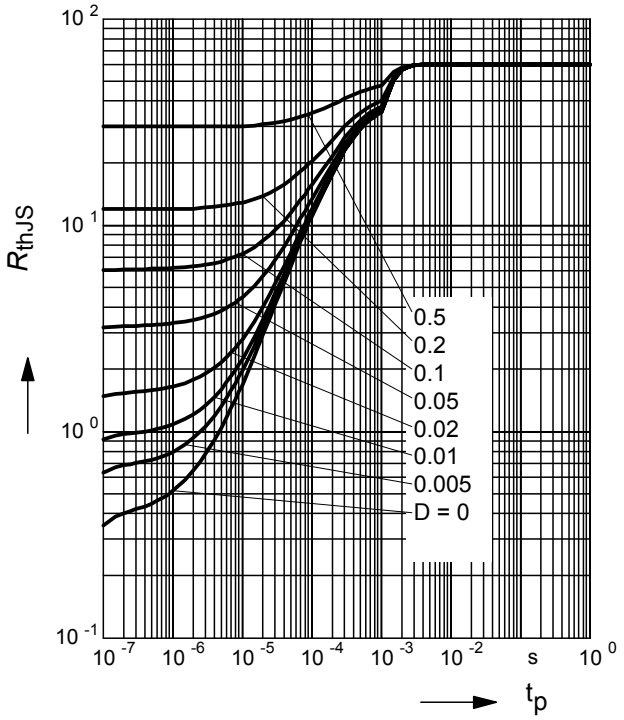
$P_{totmax}/P_{totDC} = f(t_p)$

BCR162F



Permissible Puls Load $R_{thJS} = f(t_p)$

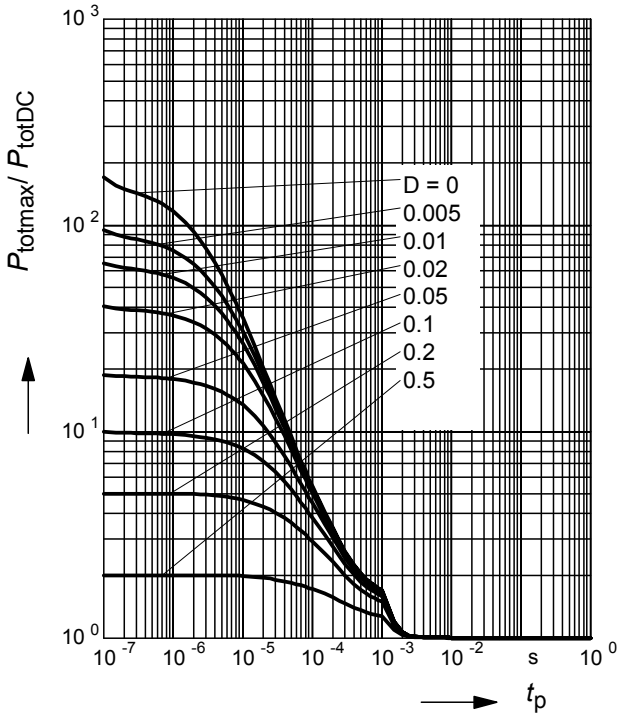
BCR162L3



Permissible Pulse Load

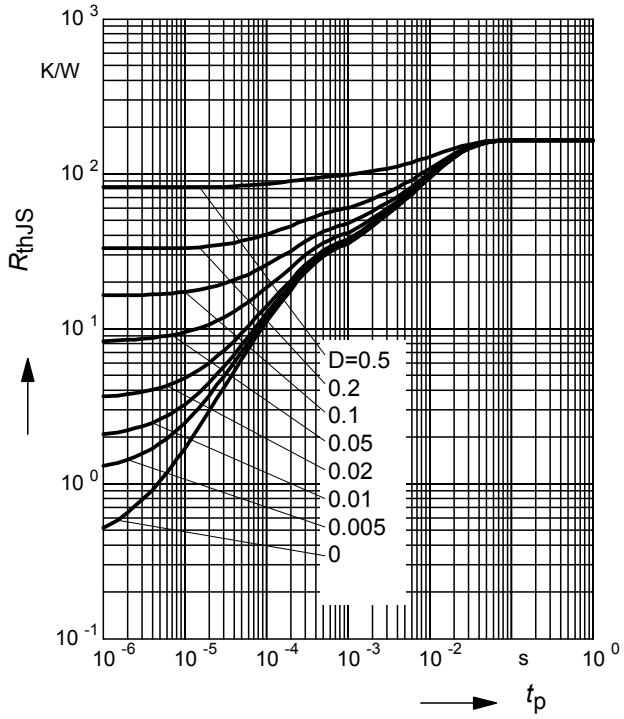
$P_{totmax}/P_{totDC} = f(t_p)$

BCR162L3



Permissible Puls Load $R_{thJS} = f(t_p)$

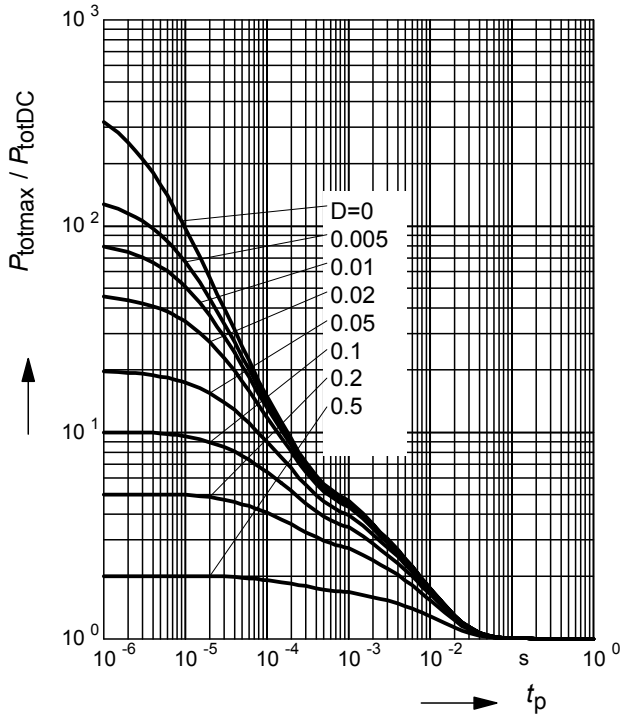
BCR162T



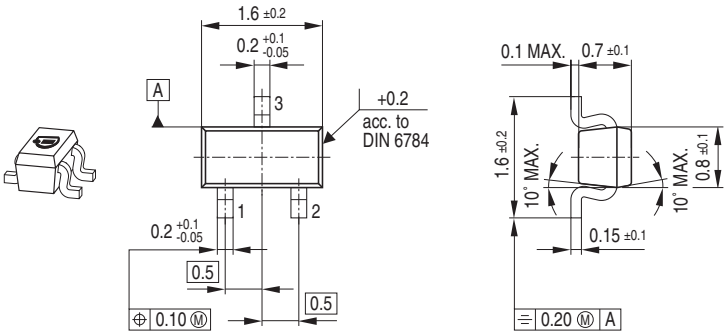
Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$

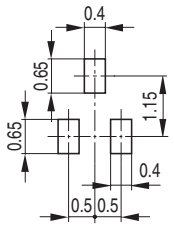
BCR162T



Package Outline



Foot Print



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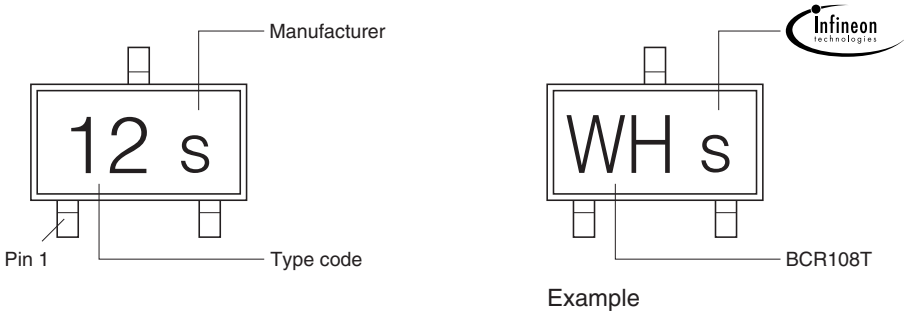
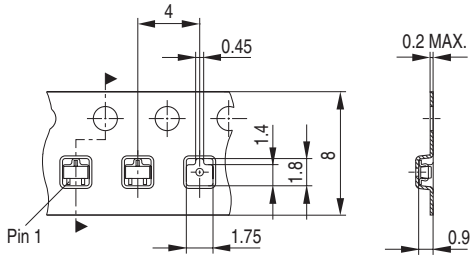


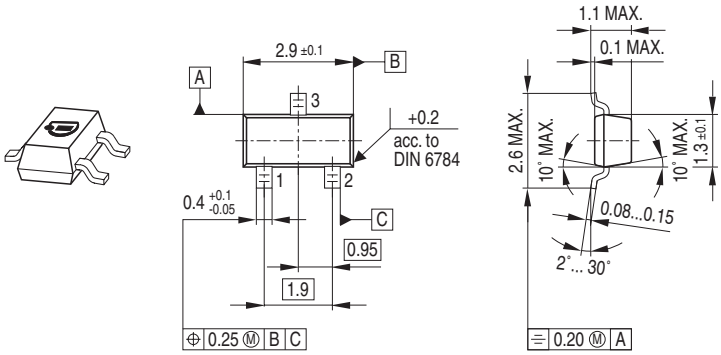
Example

Packing

Code E6327: Reel ø180 mm = 3.000 Pieces/Reel
Code E6433: Reel ø330 mm = 10.000 Pieces/Reel



Package Outline



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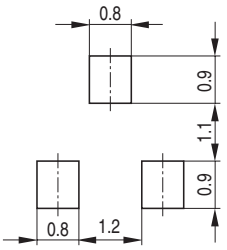

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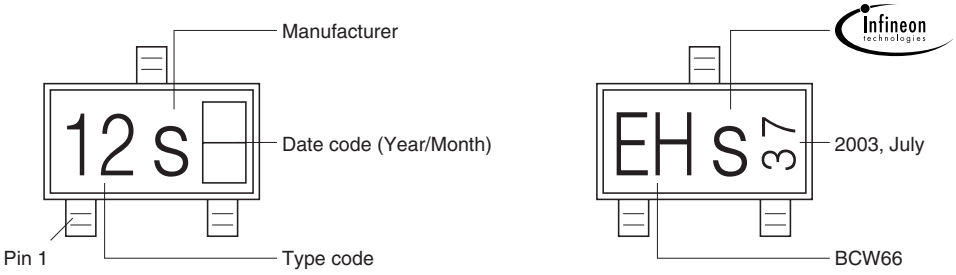

Example

Packing

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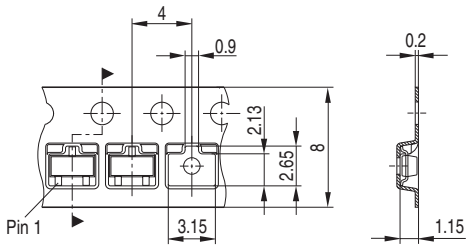
Code E6433: Reel ø330 mm = 10.000 Pieces/Reel



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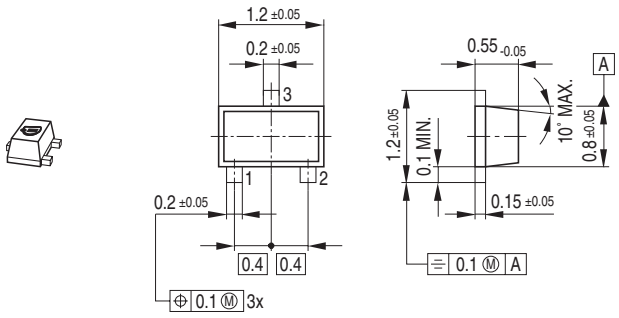

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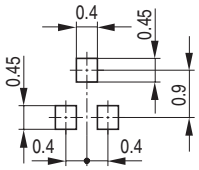

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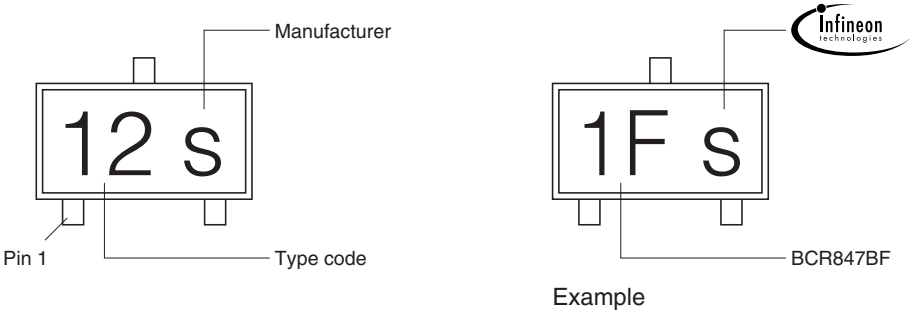
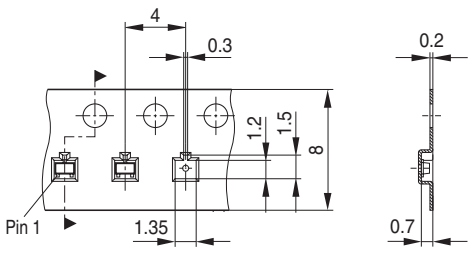


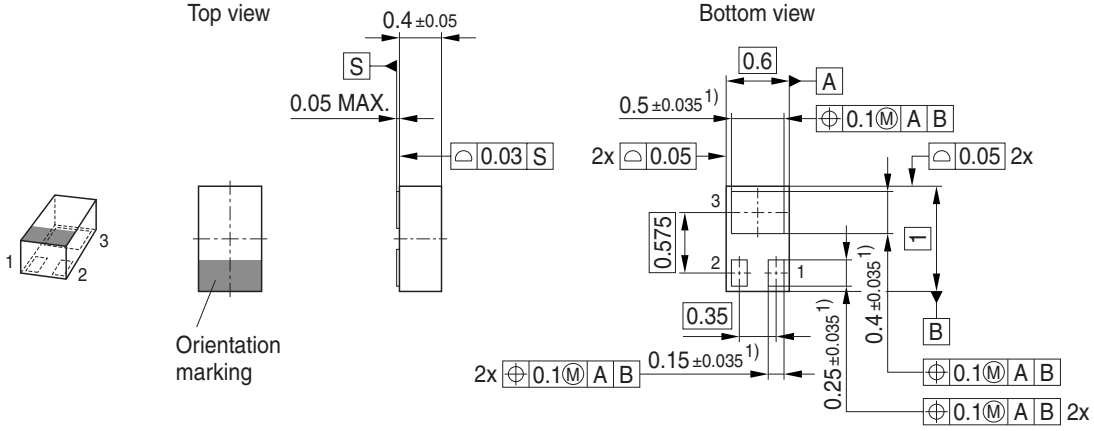
Example

Packing

Code E6327: Reel ø180 mm = 3.000 Pieces/Reel
Code E6433: Reel ø330 mm = 10.000 Pieces/Reel

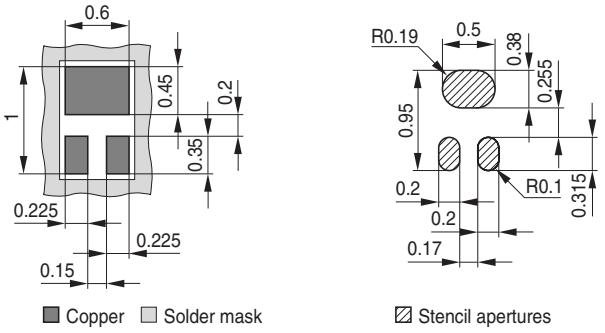


Package Outline



1) Dimension applies to plated terminals

Foot Print



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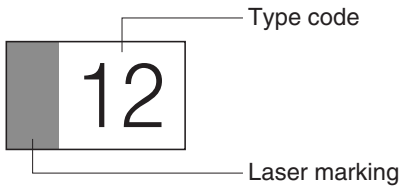
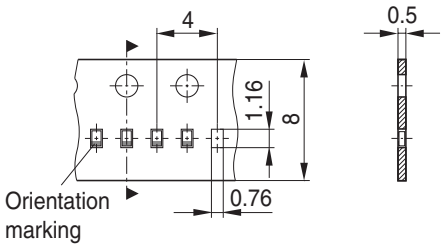


Packing

Code E6327: Reel ø180 mm = 15.000 Pieces/Reel



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